EASCERA

EAS CORPORATION

SPECIFICATION FOR APPROVAL

CUSTOMER	:	
PRODUCT TYPE	:	SMD GLASS SEALING XTAL 5.0 × 3.2
NOMINAL FREQ.	:	11.059200MHz
EAS P/N	:	EAS5032GB11.059K0DJR1
REVISION	:	A1
CUSTOMER P/N	:	
PM / SALES	:	
DATE	:	

CUSTOMER SIGNATURE & Date

(1)EAS requires one copy returned with signature and title of authorized individual that signifies acceptance of the attached specifications.

(2) Orders received and accepted by EAS after return of signed copy of specification will be produced per these specifications.

(3) Any changes to these specifications must be agreed upon by both parties and new revision of the Product Specification Sheet will be issued.

(4) Any issuance of purchase order prior to consigning back the Approval page of "Specification Sheets" from customers will be regarded as the agreement on the contents of these specifications.

MSL:Level 1

RoHS Compliant

Pb used in sealing glass material is exempt from EU directive

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PRODUCT SPECIFICATION SHEET

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EAS P/N	:	EAS5032GB11.059K0DJR1
REVISION	:	A1

PE/RD	QA	MFG

NOTE:

(1)Lead Free Products are "Directive 2002/95/EC of The European Parliament of 27 January 2003 on the restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment" Compliant (Attachment: SGS Test Report).

(2)Revision "Sx" is for engineering samples only. PE/RD's approval required.

(3)Revision "Ax" is production ready. PE, QA and MFG's approval required

MSL:Level 1

RoHS Compliant

Pb used in sealing glass material is exempt from EU directive

Rev	Revise page	Revise contents	Date	Ref.No.	Reviser
A1	N/A	Initial released	25-Nov-18	N/A	Allen Su

Spec Sheet Contents

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■ ELECTRICAL SPECIFICATIONS

Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature : 25±5℃

Relative humidity : 40%~70%

If there is any doubt about the results, measurement shall be made within the following limits:

Ambient temperature : 25±3℃

Relative humidity : 40%~70%

Measure equipment

Electrical characteristics measured by S&A250B or equivalent.

Crystal cutting type

The crystal is using AT CUT (thickness shear mode).

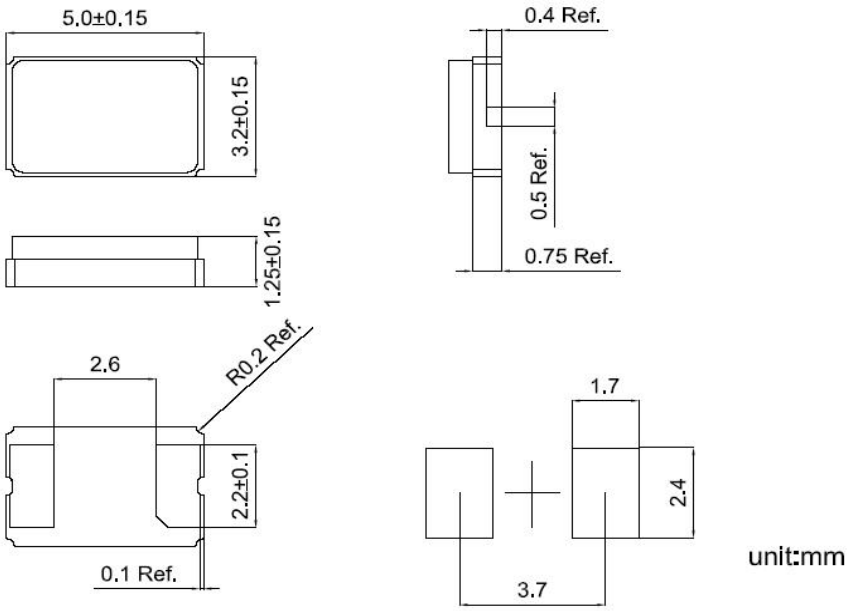
Unit Weight:

0.062±0.001 g/pcs

	Parameters	SYM.	Electrical Spec.				Notes
			MIN	TYP	MAX	UNITS	
1	Nominal Frequency	FL		11.059200		MHz	-
2	Oscillation Mode	-		Fundamental		-	-
3	Load Capacitance	CL		20		pF	-
4	Frequency Tolerance	-		±20		ppm	at 25 ± 3 ℃
5	Frequency Stability	-		±30		ppm	Over Operating Temp. Range (Reference 25℃)
6	Operating Temperature	-	-20	~	75	℃	-
7	Aging	-		±3		ppm	1st Year
8	Drive Level	DL	-	100	-	uW	-
9	Equivalent Resistance Rr	Rr	-	-	60	Ω	-
10	Shunt Capacitance C0	C0	-	-	5	pF	-
11	Insulation Resistance	-	500	-	-	MΩ	at DC 100V
12	Storage Temperature Range	-	-40	~	85	℃	-

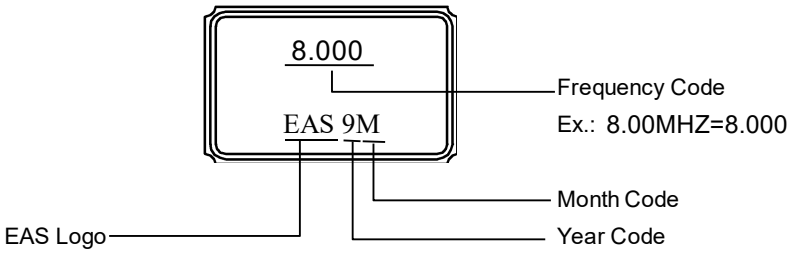
■ DIMENSIONS

(Unit:mm)



*Coplanarity of solderable areas Camber 0.10 mm Max

■ MARKING



Year Code:

2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021
0	1	2	3	4	5	6	7	8	9	0	1

Month Code:

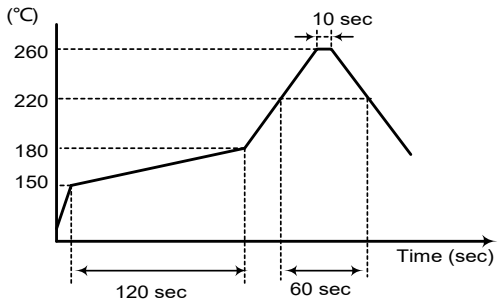
JAN	FEB	MAR	APR	MAY	JUN	JUL	AUG	SEP	OCT	NOV	DEC
A	B	C	D	E	F	G	H	I	J	K	L

Production location:CHINA

■ SUGGESTED REFLOW PROFILE

Solder melting point :220 ± 10 ℃ , 60 sec. Min

Peak Temperature: 260 ± 5 ℃ , 10 sec. Max.



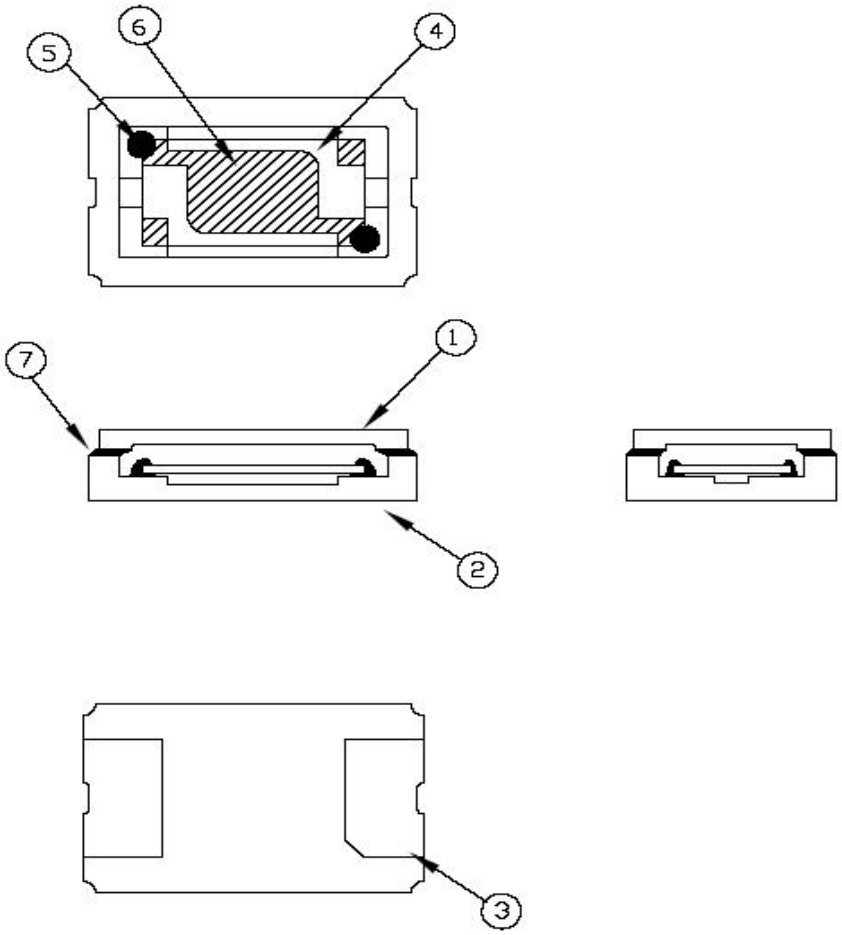
■ SUGGESTED MANUAL SOLDER CONDITION

Temperature: 350 ± 10 ℃

Time: 3 sec.

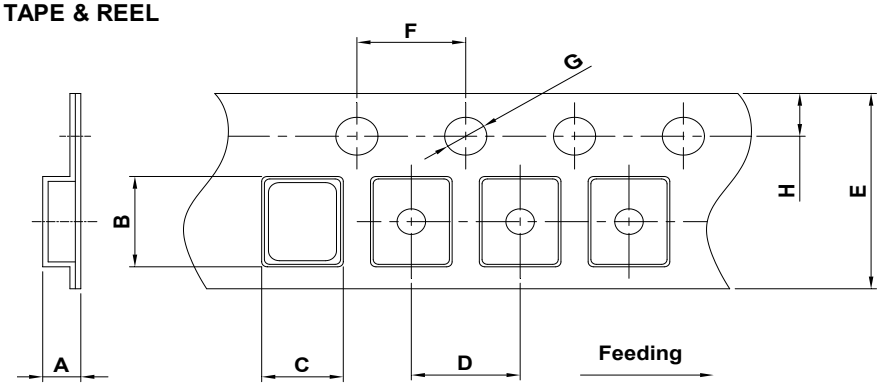
Re-solder times: twice

■ **STRUCTURE ILLUSTRATION**



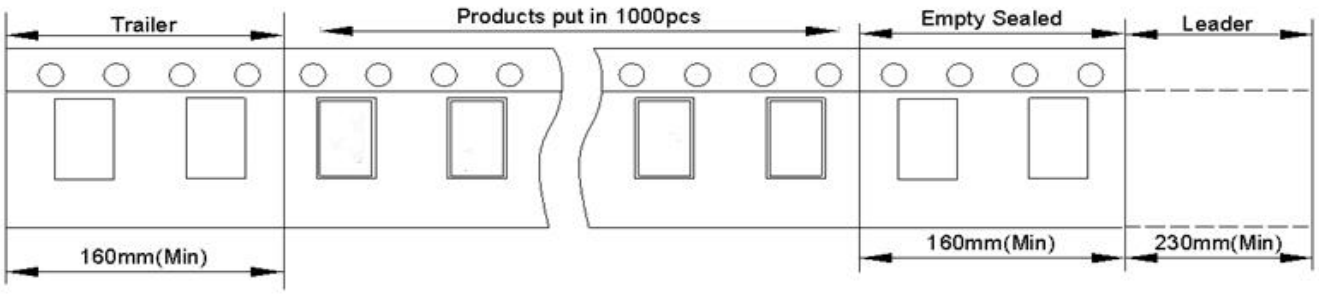
NO	COMPONENTS	MATERIALS	FINISH/SPECIFICATIONS
1	Cap	Ceramic (Al_2O_3)	-
2	Base(Package)	Ceramic (Al_2O_3)	-
3	PAD	Au	Tungsten metalize + Ni plating + Au plating
4	Crystal blank	SiO_2	-
5	Conductive adhesive	Resin+Ag	-
6	Electrode	Ag	-
7	Sealing Glass	Glass(PbO)	-

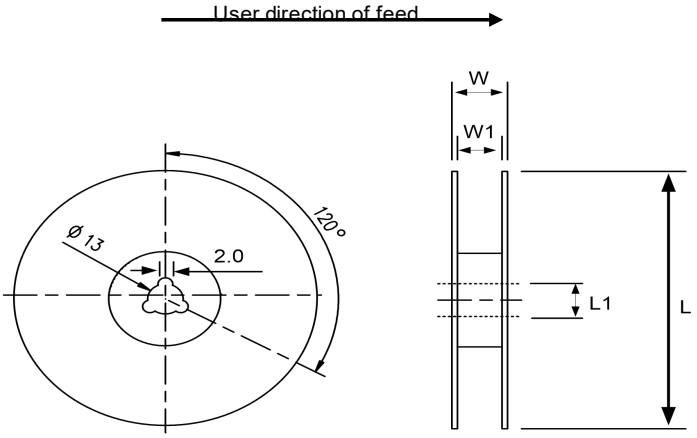
■ **EMBOSS CARRIER TAPE & REEL**



DIMENSIONS	A	B	C	D	E	F	G	H	
	1.65±0.10	5.40±0.10	3.50±0.10	8.00±0.10	12.00±0.30	4.00±0.10	1.55±0.10	1.75±0.10	(UNIT：mm)

REMARK :





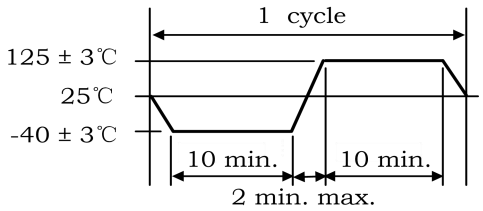
DIMENSIONS	L	L1	W	W1	
	180±1.00	13±0.50	16.5±0.20	12±0.10	(UNIT：mm)

■ RELIABILITY SPECIFICATIONS

1.Mechanical Endurance

No.	Test Item	Test Methods		Test Criteria
1.1	Drop Test	75 cm height,3 times on concrete floor .		A . C
1.2	Mechanical Shock	Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times. 0.5 ms duration time		A . C
1.3	Vibration	Frequency range Amplitude Sweep time Perpendicular axes each test time	10 ~ 2000 Hz 1.52 mm/20G 20 minutes 4 Hrs (Total test time 12 Hrs)	A . C
1.4	Solderability	Temperature Immersing depth Immersion time Flux	245 ℃ ± 5℃ 0.5 mm minimum 5 ± 1 seconds Rosin resin methyl alcohol solvent (1 : 4)	E

2.Environmental Endurance

No.	Test Item	Test Methods		Test Criteria
2.1	Resistance To Soldering Heat	Pre-heat temperature Pre-heat time Test temperature Test time	125 ℃ 60 ~ 120 sec. 260 ± 5 ℃ 10 ± 1 sec.	B . C . D
2.2	High Temp. Storage	+ 125 ℃ ± 3 ℃ for 500 ± 12 Hrs		B . C . D
2.3	Low Temp. Storage	- 40 ℃ ± 3 ℃ for 500 ± 12 Hrs		B . C . D
2.4	Temperature cycle	Total 100 cycles of the following temperature cycle 		B . C . D
2.5	High Temp＆Humidity	85℃ ± 3℃ , RH 85% , 500 Hrs		B . C . D

RELIABILITY SPECIFICATIONS

	Specifications
A	Frequency change: Within ±5ppm or in customer's specification.
B	Frequency change: Within ±10ppm or in customer's specification.
C	Equivalent series resistance(E.S.R) change: Within ±15% or 10Ω(larger value).
D	After conditioning , quartz crystal units shall be subjected to standard atmospheric conditions for 2 hour, and measured.
E	Minimum 95% of immersed terminal shall be covered with new uniform solder.

Measurement condition

Electrical characteristics measured by S&A250B or equivalent.